

WSK063

半导体晶圆切片机

WSK063 SiC slicing machine



技术规格参数 Specifications and Technical Parameters

工件 workpiece	
横断面 cross section	≤Φ330mm
长度 length	2230mm/1800mm
厚度 thickness	~0.20mm (必须调整制程 manufacturing process)
切割速率 cutting rate	
线速 wire velocity	最大 Max 30m/s 速度 Speed
快速移动 fast move	200mm/min
工作行程 working stroke	最大 MAX 325mm
线材 wire	
芯线径 diameter of core wire (external diameter)	0.035~0.40mm
钢线长度 length of wire	按线轮而定 according to wire wheel
钢线方向 direction of wire	前进或后退切割 forward or backward/double directional cutting
预切割预切线 pre-cutting	最大 MAX 50N (按钢线直径而定) max 50N / 50g (according to diameter of wire)
导轮 guide wheel	
直径 diameter	Φ192mm
长度 length	662mm
个数 number	2
电机功率 main motor power	最大 max 33.30KW
轴距 (左右) wheelbase (left & right)	540mm
轴距 (上下) wheelbase (up & down)	1300mm 450mm
钢线筒钢线轮 wire section	
直径 diameter	160mm
个数 number	2x3(b)
卷绕轴 wire winding coil	
卷绕轴工作高度 working height of winding shaft	1350mm
卷绕盘 winding coil	WSK02733-ZF361
卷绕盘容量 winding coil capacity	300L
卷绕盘最大容量 capacity of winding coil	300L
卷绕盘温度控制 temperature constant	可预设温度 optional preset temperature
卷绕盘转速 winding rate	最大 MAX 1200rpm 为线轮 伸中轴上并开在 max 1200rpm, the core wire with the center and display
冷却液流入温度 inflow temperature of cooling water	可预设温度 optional preset temperature
类型 type	
类型 type	SPS控制 系列 带集成PC SPS controller S series with integrated PC
供货商 supplier	
供货商 supplier	上海自动化仪表有限公司 Shanghai Automation Instrument Co., Ltd.
外观尺寸及总重量 outline dimension and total weight	
长度 length	4470 4410 (不含线架)
宽度 width	2170mm 2170mm
高度 height	2500mm
总重量 total weight	41300kg

设备用途和特点

- 本机广泛应用于半导体行业，用于半导体晶片的切片。是半导体行业切片加工的主要设备。最大可切片直径为330mm，切片厚度最小为0.2mm。必须调整制程。一次装夹最大可切片达1300-2230mm是半导体行业切片加工的首选设备。
- 本机特点：
 - 1、两个钢线导轮驱动（收）线驱动（放）线驱动。线速可调。线速与线径成正比。且可双向。
 - 2、钢线张力的控制是通过伺服电机（恒力）控制。
 - 3、工件进给由伺服电机通过滚珠丝杠控制。进给速度与大小与钢线的张力成正比。
 - 4、切削液的搅拌与输送。切削液管道通过滚珠丝杠控制。及计量计算。与切片速度成正比。
 - 5、本机底为高新技术集中产品。

Applications and structural features

- the machine is used for cutting semiconductor bar, which is main machine in processing equipment. The max dimension of cross section is 330mm, the minimum thickness of section is 0.2mm. adjust procedure. it may cut 1300-2230mm at one clamping. the optimized equipment for semi-conductor manufacturers.
- features:
 - two wire guide wheel drive, up and down wire drive and wire velocity adjustable.
 - generation control of wire tension can be controlled by servo motor (constant).
 - workpiece feed is driven by user's motor through ball screw, feed rate is proportional to wire tension.
 - agitation and conveying of cutting fluid. cutting fluid pipe can reach up constant temperature through heat exchanger, material of the fluid slicing rate.
- this machine is an integrated high-tech product.